

The Electronics Division Hoffman Scholarship Application Form

2018 Essay Topic:   
“Tailoring Material Properties through Defect Engineering for Electronic Ceramics”

Application Deadline: May 15th annually

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| Full Name | |
| Email Address |  |
| Mailing Address | |
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|  | |
| Name of Undergraduate Department | |
| University | |
| Total GPA Science GPA Total Credits | |
| PSAT/SAT/ACT Scores | Date of Exam |
| Extracurricular Activities | |
| (attach additional sheets if necessary) | |
|  | |
| Faculty Advisor\* | |
| Address | |
|  |  |
|  |  |
| Telephone | ( ) E-mail |
| Applicant's Signature | Date |
| Advisor's Signature | Date |
| \* Essay and Recommendation letter must be emailed directly to: | |
| Hui (Claire) Xiong  Boise State University   [clairexiong@boisestate.edu](mailto:clairexiong@boisestate.edu)    Phone: 208.426.5671    Nominations should also be sent to Erica Zimmerman [at ezimmerman](mailto:mstout@ceramics.org)@ceramics.org. | |